

# FPN660/FPN660A

### **PNP Low Saturation Transistor**

- These devices are designed for high current gain and low saturation voltage with collector currents up to 3.0A continuous.
- · Sourced from process PA.



# Absolute Maximum Ratings TA=25°C unless otherwise noted

Symbol	Parameter	FPN660	FPN660A	Units
$V_{CEO}$	Collector-Emitter Voltage	60	60	V
V <sub>CBO</sub>	Collector-Base Voltage	80	60	V
$V_{EBO}$	Emitter-Base Voltage	5	5	V
I <sub>C</sub>	Collector Current - Continuous	3	3	Α
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temperature Range	-55 ~ +150	-55 ~ +150	°C

<sup>\*</sup> These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

- These ratings are based on a maximum junction temperature of 150°C.
  These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.
  All voltage (V) and currents (A) are negative polarity for PNP transistors

# Electrical Characteristics T<sub>A</sub>=25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Off Charac	teristics	•	•	•		
BV <sub>CEO</sub>	Collector-Emitter Breakdown Voltage	I <sub>C</sub> = 10mA, I <sub>B</sub> = 0	55			٧
BV <sub>CBO</sub>	Collector-Base Breakdown Voltage	$I_E = 100 \mu A, I_E = 0$ FPN660	80			٧
		FPN660A	60			V
BV <sub>EBO</sub>	Emitter-Base Breakdown Voltage	$I_E = 100 \mu A, I_C = 0$	5.0			٧
I <sub>CBO</sub>	Collector-Base Cutoff Current	$V_{CB} = 30V, I_{E} = 0$			100	nA
		$V_{CB} = 30V, I_{E} = 0, T_{A} = 100^{\circ}C$			10	μΑ
I <sub>EBO</sub>	Emitter-Base Cutoff Current	$V_{EB} = 4.0V, I_{C} = 0$			100	nA
On Charac	teristics *					
h <sub>FE</sub>	DC Current Gain	I <sub>C</sub> = 100mA, V <sub>CE</sub> = 2.0V	70			
		$I_C = 500 \text{mA}, V_{CE} = 2.0 \text{V}$ FPN660	100		300	
		FPN660A	250		550	
		$I_C = 1.0A, V_{CE} = 2.0V$	80			
		$I_C = 2.0A, V_{CE} = 2.0V$	40			
V <sub>CE</sub> (sat)	Collector-Emitter Saturation Voltage	$I_C = 1.0A, I_B = 100mA$			300	mV
		$I_C = 2.0A, I_B = 200mA$ FPN660			450	mV
		FPN660A			400	mV
V <sub>BE</sub> (sat)	Base-Emitter Saturation Voltage	I <sub>C</sub> = 1.0A, I <sub>B</sub> = 100mA			1.25	V
V <sub>BE</sub> (on)	Base-Emitter On Voltage	$I_C = 1.0A, V_{CE} = 2.0V$			1.0	V
Small Sign	al Characteristics	•	•	-		
C <sub>obo</sub>	Output Capacitance	V <sub>CB</sub> = 10V, I <sub>E</sub> = 0, f = 1MHz			45	pF
f <sub>T</sub>	Transition Frequency	$I_C = 100 \text{mA}, V_{CE} = 5.0 \text{V},$ f = 100 MHz	75			MHz

<sup>\*</sup> Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2.0%

NOTE: All voltage (V) and currents (A) are negative polarity for PNP transistors.

#### Thermal Characteristics $\rm T_A=25^{\circ}C$ unless otherwise noted Max. Symbol Parameter Units FPN660/FPN660A W Total Device Dissipation 50 °C/W $R_{\theta JC}$ Thermal Resistance, Junction to Case Thermal Resistance, Junction to Ambient 125 °C/W $R_{\theta JA}$

# **Typical Characteristics**

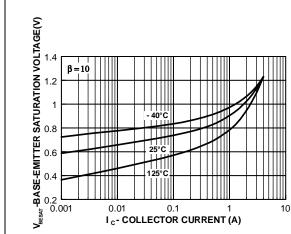


Figure 1. Base-Emitter Saturation Voltage vs Collector Current

Collector-Emitter Saturation

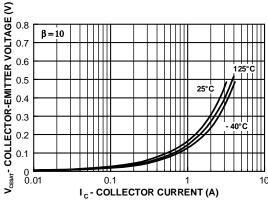


Figure 3. Collector-Emitter Saturation Voltage vs Collector Current

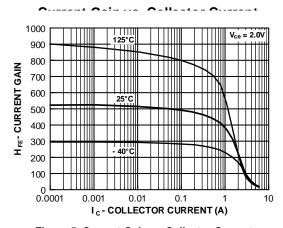


Figure 5. Current Gain vs Collector Current

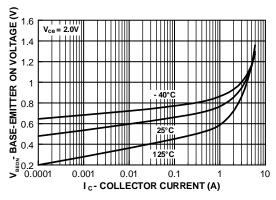


Figure 2. Base-Emitter On Voltag vs Collector Current

Innut/Outnut Conscitance ve

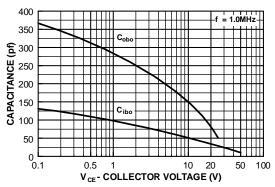


Figure 4. Input/Output Capacitance vs Reverse Bias Voltage

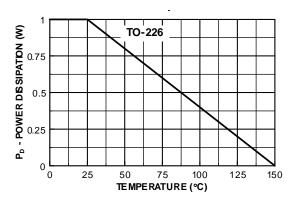
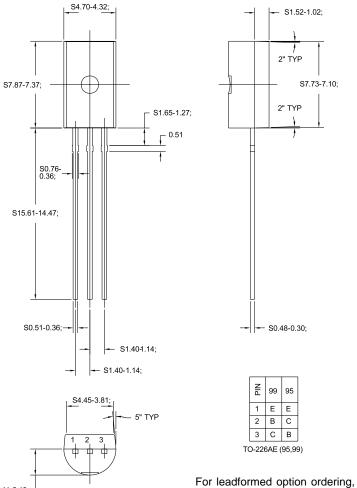


Figure 6. Power Dissipation vs Ambient Temperature

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# TO-226



refer to Tape & Reel data information.

Dimensions in Millimeters

S2.41-2.13;

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CROSSVOLT™	FRFET™	MicroPak™	QFET™	SuperSOT™-8
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Programmable Active Droop™		OPTOPLANAR™	SMART START™	

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Rev. I1

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